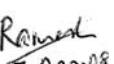


LS75

RELIABILITY DATA

DWG. No PA583-57-01		
APPD	CHK	DWG
 7 Apr 08	 7 Apr 08	 07 April 08

I N D E X

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※ The above data is typical value. As all units have nearly the same characteristics, the data to be considered as ability value.

1. Calculated values for MTBF

MODEL : LS75-5

1. Calculating Method

Calculated based on part count reliability projection of JEITA (RCR-9102A).

Individual failure rates l_G is given to each part and MTBF is calculated by the count of each part.

Formula :

$$MTBF = \frac{1}{l_{equip}} = \frac{1}{\sum_{i=1}^n N_i (l_G p_Q)_i} \times 10^6 \text{ (HOURS)}$$

where :

l_{equip} = Total Equipment Failure Rate (Failure / 106 Hours)

l_G = Generic Failure Rate For The ith Generic Part (Failure / 106 Hours)

N_i = Quantity of ith Generic Part

n = Number of Different Generic Part Categories

p_Q = Generic Quality Factor for the ith Generic Part ($p_Q = 1$)

2. MTBF Values

G_F : (GROUND, FIXED)

MTBF = 691,400 (Hours)

2. Component derating

MODEL : LS75-5

(1) Calculating method

(a) Measuring Conditions

Input	:	115 , 230VAC	• Ambient temperature	:	50°C
Output	:	5V 12A(100%)	• Mounting method	:	Mounting A

(b) Semiconductors

Compared with maximum junction temperature and actual one which is calculated based on case temperature, power dissipation and thermal impedance.

(c) IC, Resistors, Capacitors, etc.

Ambient temperature, operating condition, power dissipation and so on are within derating criteria.

(d) Calculating Method of Thermal Impedance

$$\theta_{j-c} = \frac{T_{j(max)} - T_c}{P_{c(max)}} \quad \theta_{j-a} = \frac{T_{j(max)} - T_a}{P_{c(max)}} \quad \theta_{j-l} = \frac{T_{j(max)} - T_l}{P_{c(max)}}$$

T_c : Case temperature at start point of derating ; 25°C in general

T_a : Ambient temperature at start point of derating ; 25°C in general

T_j : Lead temperature at start point of derating ; 25°C in general

$P_{c(max)}$: Maximum collector(channel) dissipation
 $(P_{ch(max)})$

$T_{j(max)}$: Maximum junction(channel) temperature
 $(T_{ch(max)})$

(θ_{j-c}) : Thermal impedance between junction(channel) and case
 (θ_{ch-c})

θ_{j-a} : Thermal impedance between junction and air

θ_{j-l} : Thermal impedance between junction and lead

(2) Component Derating List

Location No.	Vin = 115VAC Load = 100% Ta = 50°C
Q2 STF11NM60N ST MICROELECTRONICS	Tchmax = 150°C, $\theta_{j-c} = 3.57^{\circ}\text{C}/\text{W}$, Pch = 3.65W, $\Delta T_c = 31.0^{\circ}\text{C}$, $T_{ch} = T_c + ((\theta_{ch-c}) \times P_{ch}) = 94.0^{\circ}\text{C}$ D.F. = 62.7%
D8 STPS30H60CFP ST MICROELECTRONICS	Tjmax = 175°C, $\theta_{j-c} = 3.95^{\circ}\text{C}/\text{W}$ Pd = 7W, $\Delta T_c = 66.3^{\circ}\text{C}$ $T_j = T_c + ((\theta_{j-c}) \times P_d) = 144.0^{\circ}\text{C}$ D.F. = 82.3%
D1 RS405M RECTRON	Tjmax = 150°C, $\theta_{j-c} = 6.5^{\circ}\text{C}/\text{W}$, Pd = 2.24W, $\Delta T_c = 44.2^{\circ}\text{C}$, $T_j = T_c + ((\theta_{j-c}) \times P_d) = 108.8^{\circ}\text{C}$ D.F. = 72.5%
D2 CRF02(TE85L,Q) TOSHIBA	Tjmax = 150°C, $\theta_{j-l} = 20^{\circ}\text{C}/\text{W}$, Pd = 0.1W, $\Delta T_c = 57.1^{\circ}\text{C}$, $T_j = T_c + ((\theta_{j-c}) \times P_d) = 109.1^{\circ}\text{C}$ D.F. = 72.7%
D6 CRH01(TE85L,Q) TOSHIBA	Tjmax = 150°C, $\theta_{j-c} = 20^{\circ}\text{C}/\text{W}$ Pd = 0.05W, $\Delta T_c = 38.2^{\circ}\text{C}$ $T_j = T_c + ((\theta_{j-c}) \times P_d) = 89.2^{\circ}\text{C}$ D.F. = 59.5 %
PC1 PS2581L2-E3(D)-A (TRANSISTOR) NEC	Tjmax = 125°C, $\theta_{j-c} = 150^{\circ}\text{C}/\text{W}$, Pc = 2mW, $\Delta T_a = 37.9^{\circ}\text{C}$, $T_j = T_a + ((\theta_{j-a}) \times P_c) = 87.9^{\circ}\text{C}$ D.F. = 70.3%
PC1 PS2581L2-E3(D)-A (LED) NEC	Tjmax = 125°C, $\theta_{j-c} = 150^{\circ}\text{C}/\text{W}$, Pc = 0.012W, $\Delta T_a = 37.9^{\circ}\text{C}$, $T_j = T_a + ((\theta_{j-a}) \times P_c) = 89.7^{\circ}\text{C}$ D.F. = 71.8%
PC2 PS2581L2-E3(D)-A (TRANSISTOR) NEC	Tjmax = 125°C, $\theta_{j-c} = 150^{\circ}\text{C}/\text{W}$, Pc = 0W, $\Delta T_a = 41.4^{\circ}\text{C}$, $T_j = T_a + ((\theta_{j-a}) \times P_c) = 91.4^{\circ}\text{C}$ D.F. = 73.1%
PC2 PS2581L2-E3(D)-A (LED) NEC	Tjmax = 125°C, $\theta_{j-a} = 150^{\circ}\text{C}/\text{W}$, Pc = 0W, $\Delta T_a = 41.4^{\circ}\text{C}$, $T_j = T_a + ((\theta_{j-a}) \times P_c) = 91.4^{\circ}\text{C}$ D.F. = 73.1%
A1 HA17L431AP-TZ-E RENESAS	Tjmax = 150°C, $\theta_{j-c} = 100^{\circ}\text{C}/\text{W}$, Pd = 8mW, $\Delta T_c = 21.1^{\circ}\text{C}$, $T_j = T_c + ((\theta_{j-c}) \times P_d) = 71.9^{\circ}\text{C}$ D.F. = 47.9%
A2 FA13842N-D1-TE1 FUJI-ELEC.	Tjmax = 150°C, $\theta_{j-c} = 72^{\circ}\text{C}/\text{W}$ Pd = 0.1W, $\Delta T_c = 38.2^{\circ}\text{C}$ $T_j = T_c + ((\theta_{j-c}) \times P_d) = 95.4^{\circ}\text{C}$ D.F. = 63.6%
PD1 WP1154GD KING BRIGHT	IF = 6mA, $\Delta T_c = 13.8^{\circ}\text{C}$ Allowable IF(max)= 12mA(at Ta = 63.8°C) D.F. = 50%

Component Derating List

Location No.	Vin = 230VAC Load = 100% Ta = 50°C
Q2 STF11NM60N ST MICROELECTRONICS	Tchmax = 150°C, $\theta_{j-c} = 3.57^\circ\text{C}/\text{W}$, Pch = 3.2W, $\Delta T_c = 31.1^\circ\text{C}$, $T_c = 81.1^\circ\text{C}$ $T_{ch} = T_c + ((\theta_{ch-c}) \times Pch) = 99.6^\circ\text{C}$ D.F. = 61.7%
D8 STPS30H60CFP ST MICROELECTRONICS	Tjmax = 175°C, $\theta_{j-c} = 3.95^\circ\text{C}/\text{W}$ Pd = 7W, $\Delta T_c = 65.0^\circ\text{C}$ $T_c = 115.0^\circ\text{C}$ $T_j = T_c + ((\theta_{j-c}) \times Pd) = 142.7^\circ\text{C}$ D.F. = 81.5%
D1 RS405M RECTRON	Tjmax = 150°C, $\theta_{j-c} = 6.5^\circ\text{C}/\text{W}$, Pd = 1.40W, $\Delta T_c = 30.6^\circ\text{C}$, $T_c = 80.6^\circ\text{C}$ $T_j = T_c + ((\theta_{j-c}) \times Pd) = 89.7^\circ\text{C}$ D.F. = 59.8%
D2 CRF02(TE85L,Q) TOSHIBA	Tjmax = 150°C, $\theta_{j-l} = 20^\circ\text{C}/\text{W}$, Pd = 0.1W, $\Delta T_c = 57.1^\circ\text{C}$, $T_c = 107.1^\circ\text{C}$ $T_j = T_c + ((\theta_{j-c}) \times Pd) = 109.1^\circ\text{C}$ D.F. = 72.7%
D6 CRH01(TE85L,Q) TOSHIBA	Tjmax = 150°C, $\theta_{j-c} = 20^\circ\text{C}/\text{W}$ Pd = 0.05W, $\Delta T_c = 39.1^\circ\text{C}$ $T_c = 89.1^\circ\text{C}$ $T_j = T_c + ((\theta_{j-c}) \times Pd) = 90.1^\circ\text{C}$ D.F. = 60.0 %
PC1 PS2581L2-E3(D)-A (TRANSISTOR) NEC	Tjmax = 125°C, $\theta_{j-a} = 150^\circ\text{C}/\text{W}$, Pc = 2mW, $\Delta T_a = 38.0^\circ\text{C}$, $T_a = 88.0^\circ\text{C}$ $T_j = T_a + ((\theta_{j-a}) \times P_c) = 88.0^\circ\text{C}$ D.F. = 70.4%
PC1 PS2581L2-E3(D)-A (LED) NEC	Tjmax = 125°C, $\theta_{j-a} = 150^\circ\text{C}/\text{W}$, Pc = 0.012W, $\Delta T_a = 38.0^\circ\text{C}$, $T_a = 88.0^\circ\text{C}$ $T_j = T_a + ((\theta_{j-a}) \times P_c) = 90^\circ\text{C}$ D.F. = 72.0%
PC2 PS2581L2-E3(D)-A (TRANSISTOR) NEC	Tjmax = 125°C, $\theta_{j-a} = 150^\circ\text{C}/\text{W}$, Pc = 0W, $\Delta T_a = 41.8^\circ\text{C}$, $T_a = 91.8^\circ\text{C}$ $T_j = T_a + ((\theta_{j-a}) \times P_c) = 91.8^\circ\text{C}$ D.F. = 73.4%
PC2 PS2581L2-E3(D)-A (LED) NEC	Tjmax = 125°C, $\theta_{j-a} = 150^\circ\text{C}/\text{W}$, Pc = 0W, $\Delta T_a = 41.8^\circ\text{C}$, $T_a = 91.8^\circ\text{C}$ $T_j = T_a + ((\theta_{j-a}) \times P_c) = 91.8^\circ\text{C}$ D.F. = 73.4%
A1 HA17L431AP-TZ-E RENESAS	Tjmax = 150°C, $\theta_{j-c} = 100^\circ\text{C}/\text{W}$, Pd = 8mW, $\Delta T_c = 21.1^\circ\text{C}$, $T_c = 71.1^\circ\text{C}$ $T_j = T_c + ((\theta_{j-c}) \times Pd) = 71.9^\circ\text{C}$ D.F. = 47.9%
A2 FA13842N-D1-TE1 FUJI-ELEC.	Tjmax = 150°C, $\theta_{j-c} = 72^\circ\text{C}/\text{W}$ Pd = 0.1W, $\Delta T_c = 39.1^\circ\text{C}$ $T_c = 89.1^\circ\text{C}$ $T_j = T_c + ((\theta_{j-c}) \times Pd) = 96.3^\circ\text{C}$ D.F. = 64.2%
PD1 WP1154GD KING BRIGHT	IF = 6mA, $\Delta T_c = 13.9^\circ\text{C}$ Allowable IF(max)= 12mA(at Ta = 63.9°C) D.F. = 50%

3. Main components temperature rise ΔT list

MODEL : LS75-5

Condition:

Standard Mounting (Mounting Method (A))	(A)			
	Mounting A	Mounting B	Mounting C	Mounting D
Input Voltage (VAC)		115		
Output Voltage (VDC)		5		
Output Current (A)		12		

Output Derating $T_a = 50^\circ\text{C}$		ΔT Temperature rise ($^\circ\text{C}$)			
Location No	Parts Name	$Io=100\%$	$Io=100\%$	$Io=70\%$	$Io=100\%$
Mounting (A)	Mounting (B)	Mounting (C)	Mounting (D)		
L1	BALUN COIL	33.0	43.0	42.2	35.6
L6	CHOKE COIL	53.8	57.2	66.5	50.0
T1	TRANS PULSE	61.5	55.7	54.3	60.3
A1	I.C	21.1	23.8	37.5	20.4
A2	CHIP I.C	38.2	33.2	31.4	42.0
PD1	LED	13.8	17.1	34.1	14.2
D1	BRIDGE DIODE	44.2	49.4	48.5	49.9
D8	OUTPUT DIODE	66.3	65.6	64.2	66.2
Q2	MOS FET	31.0	31.3	29.3	35.8
C1	FILM CAP.	31.4	40.7	48.6	28.4
C2	FILM CAP	34.3	40.1	43.0	40.1
C6	E. CAP.	29.3	34.6	26.0	34.0
C18	E. CAP.	36.8	28.3	26.4	43.1
C19	E. CAP.	36.8	25.0	22.2	36.5
C23	E. CAP.	48.2	44.7	46.1	42.3
C24	E. CAP.	47.2	44.8	42.1	43.3
C25	E. CAP.	43.6	41.3	43.5	38.2
C26	E. CAP.	46.5	45.3	45.4	42.4
C27	E. CAP.	43.8	41.0	45.2	37.5
C28	E. CAP.	43.9	47.4	49.3	39.7

3. Main components temperature rise ΔT list

MODEL : LS75-5

Condition:

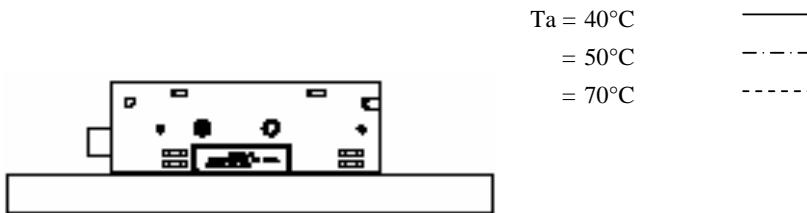
Standard Mounting (Mounting Method (A))	(A)			
	Mounting A	Mounting B	Mounting C	Mounting D
Input Voltage (VAC)		230		
Output Voltage (VDC)		5		
Output Current (A)		12		

Output Derating $T_a = 50^\circ\text{C}$		ΔT Temperature rise ($^\circ\text{C}$)			
Location No.	Parts Name	Mounting (A)	Mounting (B)	Mounting (C)	Mounting (D)
L1	BALUN COIL	24.1	33.1	30.5	25.1
L6	CHOKE COIL	54.4	57.6	66.4	50.0
T1	TRANS PULSE	63.1	56.5	55.5	60.2
A1	I.C	21.1	23.7	37.2	19.8
A2	CHIP I.C	39.1	33.5	31.6	41.9
PD1	LED	13.9	17.4	33.8	13.7
D1	BRIDGE DIODE	30.6	37.2	34.6	34.6
D8	OUTPUT DIODE	65.0	63.6	62.1	63.7
Q2	MOS FET	31.1	30.6	28.6	34.3
C1	FILM CAP.	27.7	36.8	40.1	24.3
C2	FILM CAP	26.4	33.6	32.7	29.8
C6	E. CAP.	24.6	30.6	21.8	27.4
C18	E. CAP.	37.9	28.9	27.2	43.5
C19	E. CAP.	38.2	25.7	22.9	36.5
C23	E. CAP.	45.5	42.2	43.9	39.6
C24	E. CAP.	46.0	43.2	40.9	41.5
C25	E. CAP.	41.6	39.4	41.3	36.4
C26	E. CAP.	46.0	44.1	44.2	41.3
C27	E. CAP.	43.6	40.4	44.3	36.9

4. Electrolytic capacitor lifetime

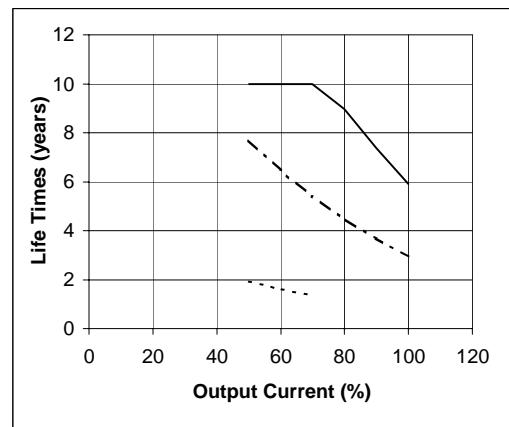
MODEL : LS75-5

Mounting A



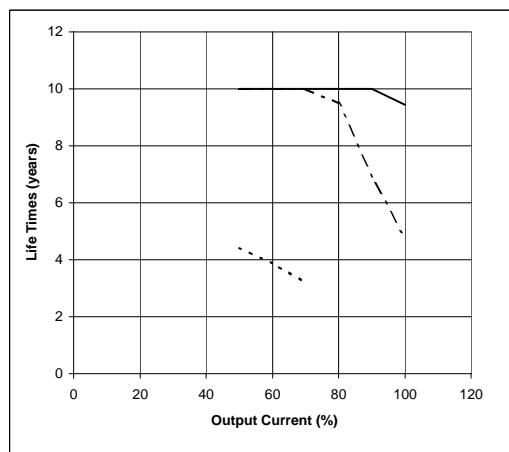
Vin = 115VAC

Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	10.0	7.7	1.9
60	10.0	6.5	1.6
70	10.0	5.4	1.3
80	9.0	4.5	-
90	7.4	3.7	-
100	5.9	3.0	-



Vin = 230VAC

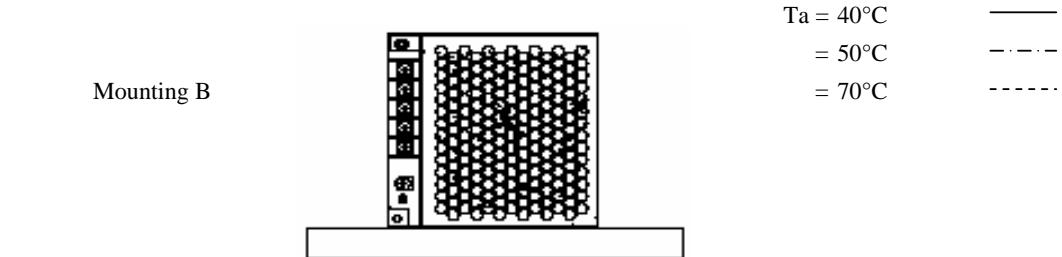
Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	10.0	10.0	4.4
60	10.0	10.0	3.9
70	10.0	10.0	3.2
80	10.0	9.5	-
90	10.0	6.9	-
100	9.4	4.7	-



Note : E-cap life calculation is based on 8hrs/day operation.

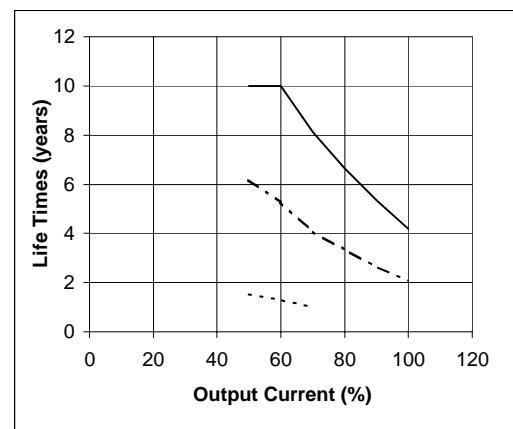
4. Electrolytic capacitor lifetime

MODEL : LS75-5



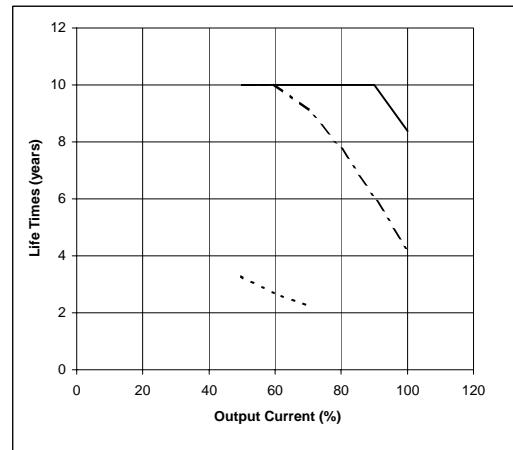
Vin = 115VAC

Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	10.0	6.2	1.5
60	10.0	5.3	1.3
70	8.1	4.1	1.0
80	6.6	3.3	-
90	5.3	2.7	-
100	4.2	2.1	-



Vin = 230VAC

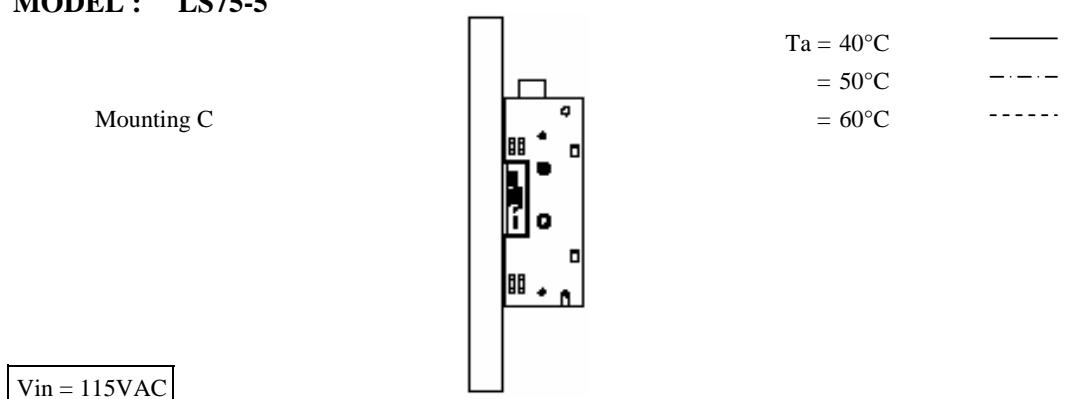
Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	10.0	10.0	3.3
60	10.0	10.0	2.7
70	10.0	9.1	2.3
80	10.0	7.8	-
90	10.0	6.1	-
100	8.4	4.2	-



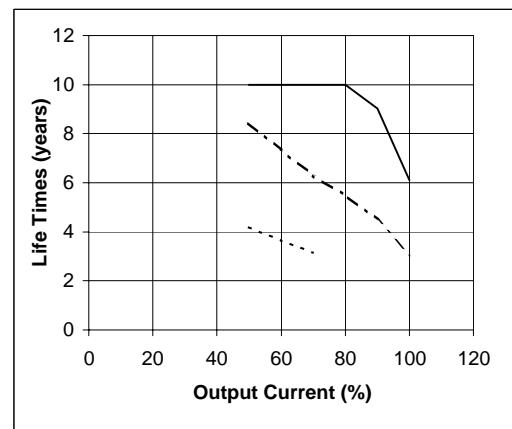
Note : E-cap life calculation is based on 8hrs/day operation.

4. Electrolytic capacitor lifetime

MODEL : LS75-5

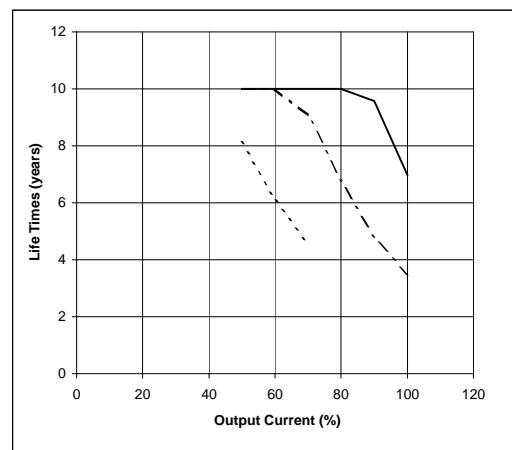


Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 60°C
50	10.0	8.4	4.2
60	10.0	7.3	3.7
70	10.0	6.3	3.1
80	10.0	5.5	-
90	9.0	4.5	-
100	6.1	3.1	-



Vin = 230VAC

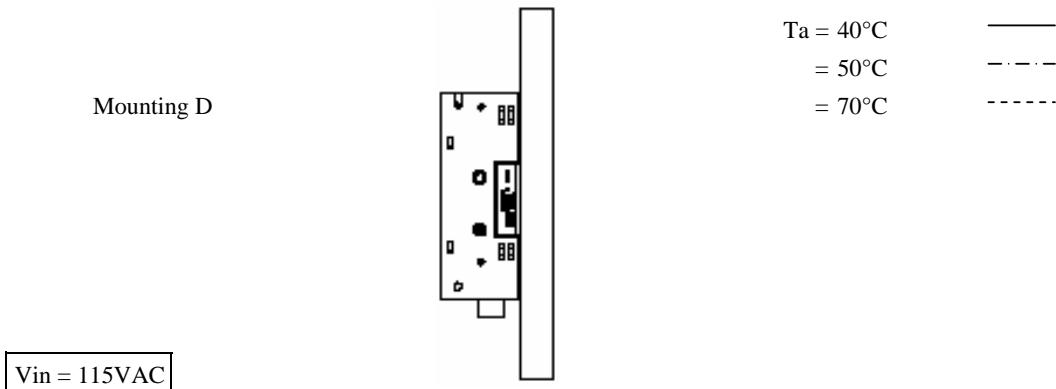
Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 60°C
50	10.0	10.0	8.1
60	10.0	10.0	6.1
70	10.0	9.1	4.5
80	10.0	6.8	-
90	9.6	4.8	-
100	7.0	3.5	-



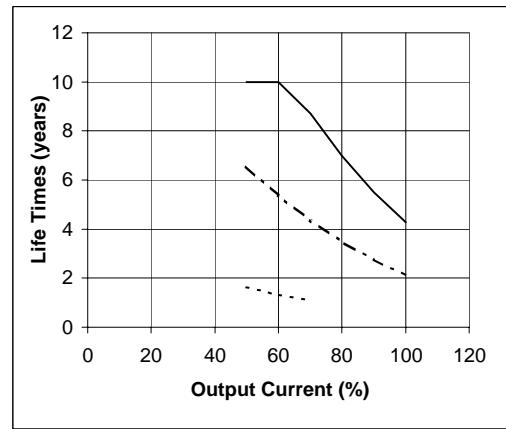
Note : E-cap life calculation is based on 8hrs/day operation.

4. Electrolytic capacitor lifetime

MODEL : LS75-5

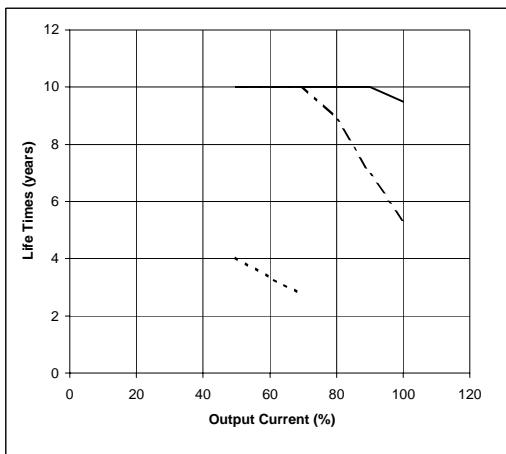


Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	10.0	6.6	1.6
60	10.0	5.4	1.3
70	8.7	4.4	1.1
80	7.0	3.5	-
90	5.5	2.8	-
100	4.3	2.1	-



Vin = 230VAC

Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	10.0	10.0	4.0
60	10.0	10.0	3.3
70	10.0	10.0	2.7
80	10.0	8.9	-
90	10.0	7.0	-
100	9.5	5.3	-



Note : E-cap life calculation is based on 8hrs/day operation.

5. Vibration Test

MODEL : LS75-5

(1) Vibration Test Class

Frequency Variable Endurance Test

(2) Equipment Used

Controller	:	F-400-BM-E47 (EMIC CORP.)
Vibrator	:	905-FN (EMIC CORP.)
Serial no.	:	22965

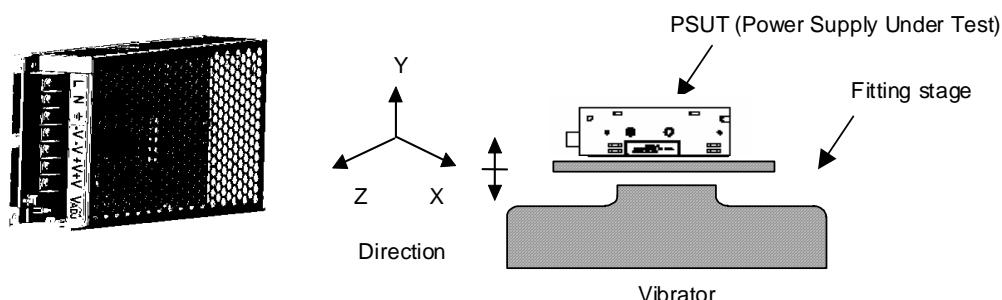
(3) The Number Of D.U.T. (Device Under Test)

1 Unit

(4) Test Conditions

Sweep Frequency	:	10 - 55Hz	Direction	:	X, Y, Z
Sweep Time	:	1 minute	Test Time	:	1 hour each axis
Acceleration	:	2G	Non-operation		
Mounting	:	A and B			

(5) Test Method



Fix the PSUT on the universal plate via two M3 tapped holes on the chassis of the power supply.
Standard mounting position as per test specification.

(6) Test results - OK

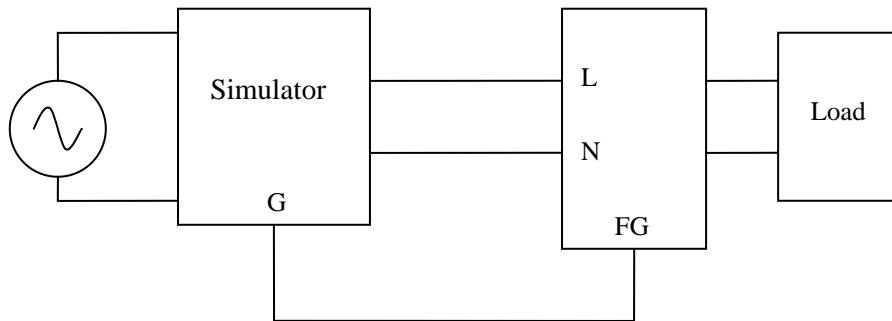
Test Conditions :	Vin	= 230 Vac	Load Condition :	
	Ambient Temp.	= +25 °C		Full Load

Check Item		Output Voltage (V)	PSUT State
Before Test		V _{o1}	
5.010			
After test	X	5.010	OK
	Y	5.010	OK
	Z	5.010	OK

6. Noise simulate test

MODEL : LS75-5

(1) Test circuit and equipment



Simulator

: INS-400L

Noise Laboratory Co.,LTD

(2) Test conditions

- | | | | | | |
|-----------------------|---|--------------|------------------|---|---------------|
| • Input voltage | : | 115, 230VAC | • Noise level | : | 0V~2.4kV |
| • Output voltage | : | Rated | • Phase shift | : | 0° ~ 360° |
| • Output current | : | 0%, 100% | • Polarity | : | +, - |
| • Ambient temperature | : | 25°C | • Mode | : | Normal Common |
| • Pulse Width | : | 0ns ~ 1000ns | • Trigger select | : | Line |

(3) Acceptable conditions

1. Not to be broken.
2. No output shutdown.
3. No other out of order.

(4) Test result O K

7. Abnormal test

MODEL : LS75-5

(1) Test Condition

Input Voltage : 230VAC Output Current : 100% Ta : 25°C, 70% RH

(2) Test Results

(Da: Damaged)

No.	Test Position		Test Mode		Test Results												NOTE
	LOCATION	TEST POINT	S H O R T	O P E N	1	2	3	4	5	6	7	8	9	10	11	12	
					F I M O R S E K T	S M U O R L E S T	B U M R E L D A H O B L O W	S M U O R L E S T	R E A D M A G E H O B L O W	D A M A G E B L O W	F U S C P B L O W	O .C V P .	O O V P .	N O O U T P U T	N O O C H A T P N G E	O T H E R	
1	D1	(+) - (-)	•								•	•			•		Da : F1
2	D2		•												•		
3	D3		•												•		
4	D4		•												•		
5	D5		•												•		
6	D7		•								•					•	Hiccup, Da : R31,R32
7	D8		•												•		No Damage Da : R33, A1
8	Q1	3 - 4	•												•	•	Latch
			•												•		
		1 - 6	•												•	•	Latch
			•												•		
		3 - 5	•												•	•	Latch
			•												•		
9	Q2	6 - 2	•												•	•	Latch
			•												•		
		G - S	•												•		
		D - G	•								•	•			•		Da : R33,Z1,Z2,F1
10	Q3	D - S	•								•	•			•		Da : F1,R33,Z2
		C - E	•												•		
		B - E	•												•		Hiccup
11	C6	C - B	•												•		Hiccup
		(+)Bulk - (-)Bulk	•								•	•			•		Da : F1
		C11/R19	•								•				•		Da : Q3,Z2
14	C11/R19	C11	•												•		
		R19	•												•		
			•												•		
12	C13		•												•		
			•												•		
13	C15		•								•	•			•		Da : Q2,F1,Z2
			•								•	•			•		

7. Abnormal test

MODEL : LS75-5

(1) Test Condition

Input Voltage : 230VAC Output Current : 100% Ta : 25°C, 70% RH

(2) Test Results

(Da: Damaged)

No.	Test Position		Test Mode		Test Results												NOTE
	LOCATION	TEST POINT	S H O R T	O P E N	1	2	3	4	5	6	7	8	9	10	11	12	
					F I M O R S E K T	S M U O R L E T	B U M S L H A O T	S E D L L G A O T	R E A M A G B L O W	D A M A G E B L O W	F U C P B .C P .	O /.C P .	O V P .	N O O U T P U T	N O O C H A N G E	O T H E R	
15	C36 OR C37		•													•	
																•	Hissing sound
16	PC1	1 - 2	•													• •	Latch
		3 - 4	•													• •	
		1 - 2		•												• •	Latch
		3 - 4		•												• •	
17	PC2	3 - 4	•													• •	
		1 - 2	•													• •	
				•												• •	
																• •	
18	A1	Vcc - GND	•													•	
		Vref - GND	•													•	
		Isense - GND	•													•	Da : Q2,Z2
		RtCt - GND	•													•	
		FB - GND	•													•	
		Comp - GND	•													•	
		Out - GND	•													•	
19	A2	A - K	•													•	
		R - K	•													•	Vo = 3.68V
		R - A	•													• •	Latch
20	T1	Np	•													•	
		Nbias	•													•	
		Ns	•													•	
21	PD1		•													•	
				•												•	
22	Z1		•													•	
				•												•	
23	Z2		•									•	•			•	Da : Q2,F1,Z2
				•												•	
24	Z4		•													•	
				•												•	
25	R9/C10	R9/C8	•													•	
		R9	•													•	
		C8	•													•	
26	R20		•													•	
				•												•	

7. Abnormal test

MODEL : LS75-5

(1) Test Condition

Input Voltage : 230VAC Output Current : 100% Ta : 25°C, 70% RH

(2) Test Results

(Da: Damaged)

No.	Test Position		Test Mode		Test Results												NOTE
	LOCATION	TEST POINT	S H O R T	O P E R E N	1	2	3	4	5	6	7	8	9	10	11	12	
					F I M O R K S E	S M U R E L T	B U M R D L H	S E L A M G O	R E D M A G E	D A M A B L O	F U S C E B L	O .C V P P .P U	N O O C U H	N O O C H A	O T H E R		
27	R29		•													•	
																•	
28	R30		•										•		•		Da : Q2,Z2,R33
29	R33		•									•			•		Da : Q2
30	R49		•											•	•	•	Latch
31	R48		•													•	Latch
32	VR1		•													•	Hissing sound
																•	Vo = 5.95
																•	Vo = 3.09

8. Thermal shock test

MODEL : LS75

(1) Equipment used

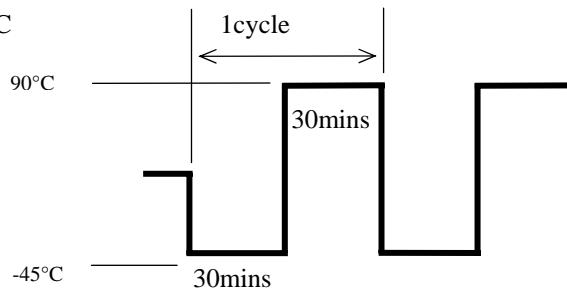
THERMAL SHOCK CHAMBER TSA-101S-W (ESPEC CORP.)

(2) The number of D.U.T.(Device Under Test)

1 unit

(3) Test Conditions

- Ambient temperature : -45°C \longleftrightarrow 90°C
- Test time : 30 mins each temp.
- Test cycle : 100 cycles
- Not operating



(4) Test Method

Before testing, check if there is no abnormal output, then put the D.U.T. in testing chamber, and test it according to the above cycle. 100 cycles later, leave it for 1 hour at the room temperature, then check if there is no abnormal output.

(5) Test Results **OK**

Vin : 230VAC Io : 100%		48V					
		From		To			
Ripple&Spike noise		mV	14.4		24		
Line regulation	Full load	mV	16		28		
Load regulation	Vin:115V	mV	14		9		
Efficiency	Pin	W	87.13		86.74		
	Vout	V	47.903	87.97%	47.668		87.93%
	Iout	A	1.60		1.60		
Solder condition • etc.			<hr/>		OK		